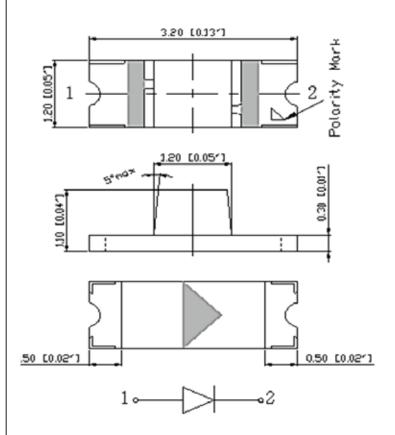
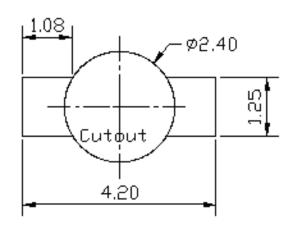


SPECIFICATION CS124AR2C-R

PACKAGE OUTLINES



RECOMMENDED SOLDER PAD



ITEM	MATERIALS		
Resin (mold)	Ероху		
Lens Color	Water Transparent		
Dice	AlGaInP/GaAs		
Emitted Color	Red		

Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is \pm 0.25mm (0.01") unless otherwised noted.
- 3. Specifications are subject to change without notice.

Part Number Chip Material		Color of Emission	Lens Type	Viewing Angle	
CS124AR2C-R	InGaAIP	Red	Water Clear	140°	





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	30	mA	
Reverse Current @ 5V	lR	10	μΑ	
Power Dissipation	Pd	75	mW	
Operating Temperature Range	Тор	-40~+85	°C	
Storage Temperature Range	Тѕтс	-40~+85	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lFP	125	mA	
Soldering Temperature	TsoL	Max 260°C for 5 sec Max		

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Parameter	Symbol	Test Condition	Value			l lait
			Min	Тур	Max	Unit
Luminous Intensity	lv	IF = 20mA	50	110	-	mcd
Forward Voltage	VF	IF = 20mA	1	2.0	2.5	V
Reverse Leakage Current	lR	VR = 5V	-	-	10	μΑ
Viewing Angle at 50% Iv	201/2	IF = 20mA	ı	140	-	Deg
Peak Wavelength	λР	IF = 20mA	-	640	-	nm
Dominant Wavelength	λD	IF = 20mA	625	630	635	nm

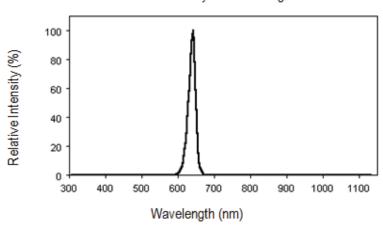
^{*}Tolerance of viewing angle: -10 / +5 deg.



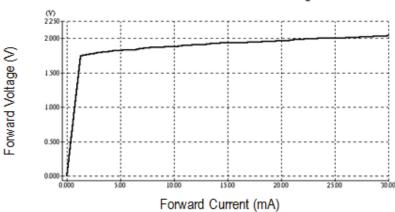


OPTICAL CHARACTERISTIC CURVES

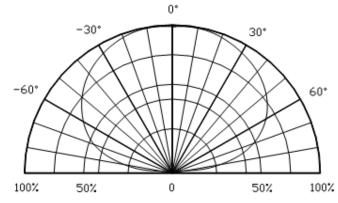
Relative Intensity vs. Wavelength



Forward Current vs. Forward Voltage



Directive Characteristics



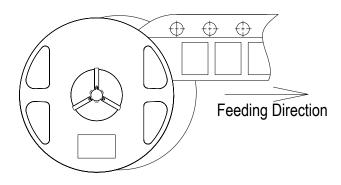
RoHS Compliant



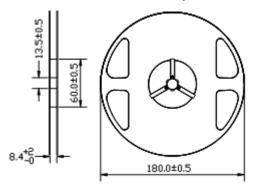
PACKAGING SPECIFICATION

PACKAGING SPECIFICATIONS

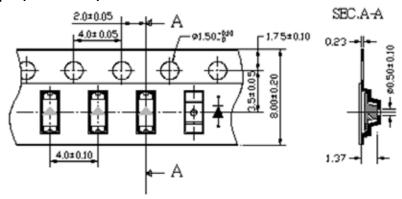
Feeding Direction



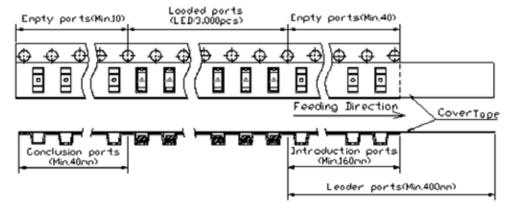
Dimensions of Reel (Unit: mm)



Dimensions of Tape (Unit: mm)



Arrangement of Tape



Notes:

- 1. Empty component pockets are sealed with top cover tape
- 2. Maximum number of missing lamp is two
- 3. Cathode is oriented towards the tape sprocket hole
- 4. 3,000 pcs/Reel

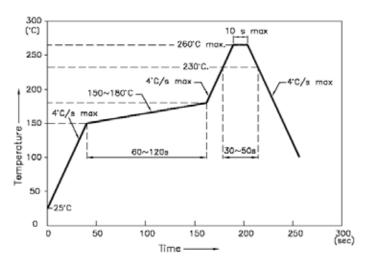




SOLDERING CONDITIONS

SOLDERING PROFILE

Reflow Temp/Time



- We recommend the reflow temperature 245°C (±5 °C) & the maximum soldering temperature should be limited to 260 °C.
- Do not cause stress to the epoxy resin while it is exposed to high temperature.
- Number of reflow process should be 2 times or less.
- Soldering Iron:
 - Basic spec is ≤ 5 sec when 260 °C. If the temperature is higher, time should be shorter (+10 °C → -1 sec). Power dissipation of iron should be smaller than 20W and temperature should be controllable. Surface temperature of the device should be under 230 °C.
- Rework:
 - Customer must finish rework within 5 sec under 260 °C
 - The head of iron cannot touch copper foil
 - Twin-head type is preferred

